

FIG. 1

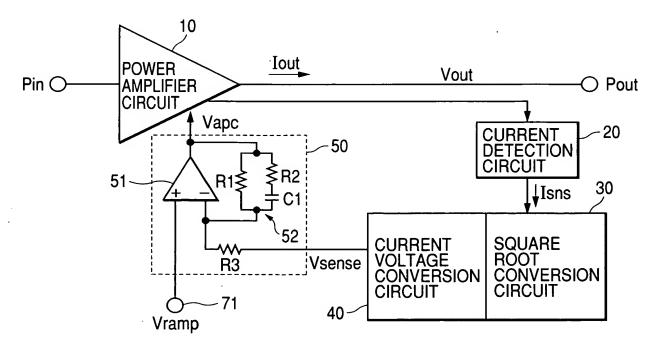
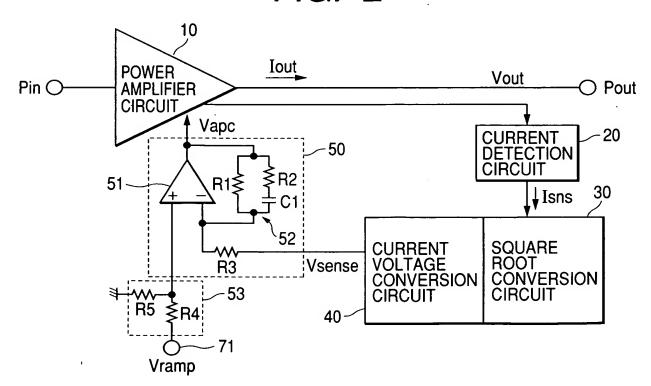
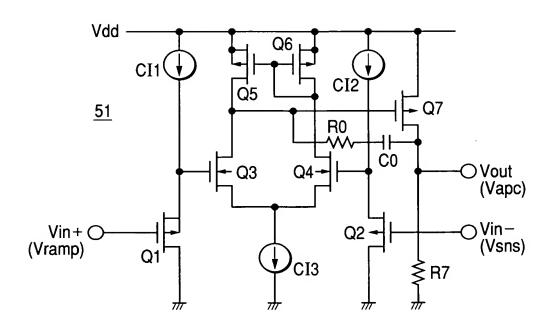


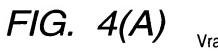
FIG. 2



TAKAHASHI et al Page 2 of 10 HITA.0533

FIG. 3











TAKAHASHI et al HITA.0533 Page 3 of 10

.3 / 10

FIG. 5(A)

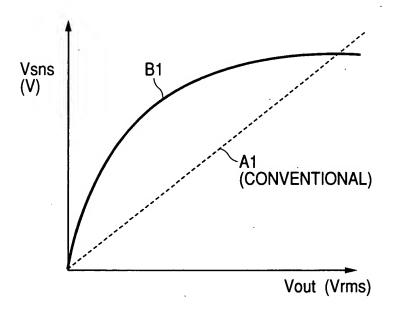
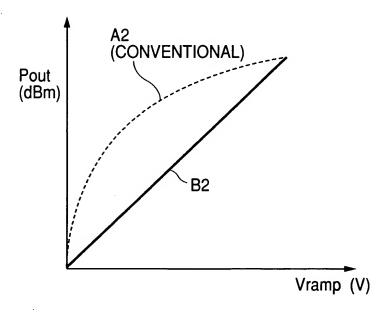


FIG. 5(B)



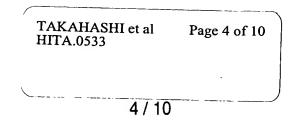


FIG. 6(A)

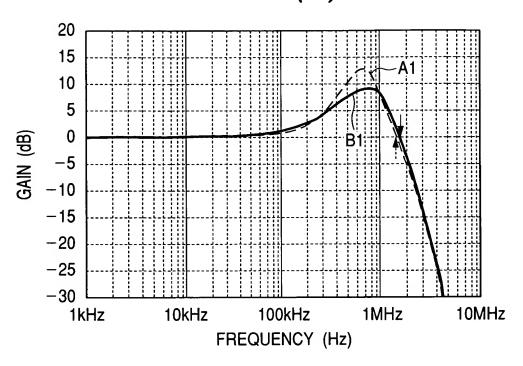
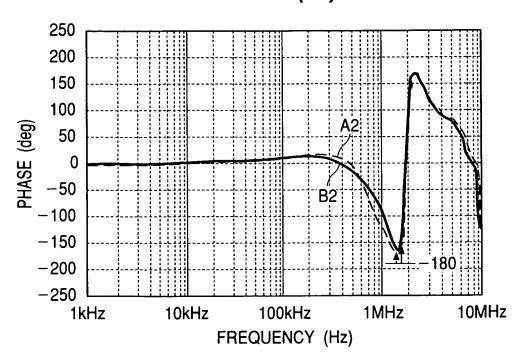


FIG. 6(B)



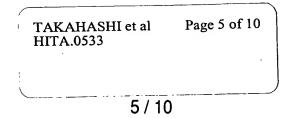


FIG. 7(A)

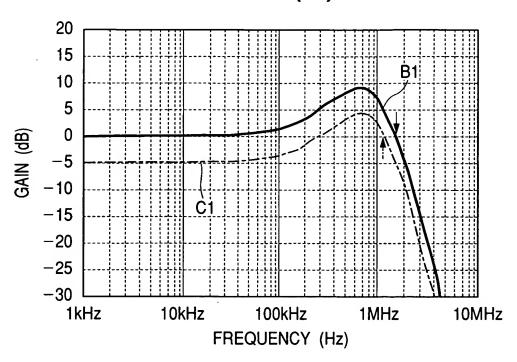
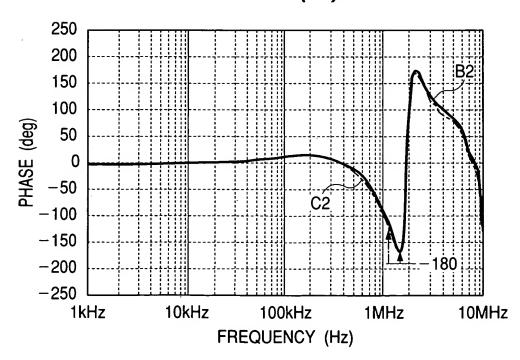


FIG. 7(B)



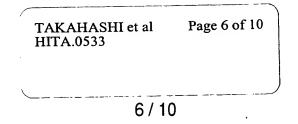


FIG. 8(A)

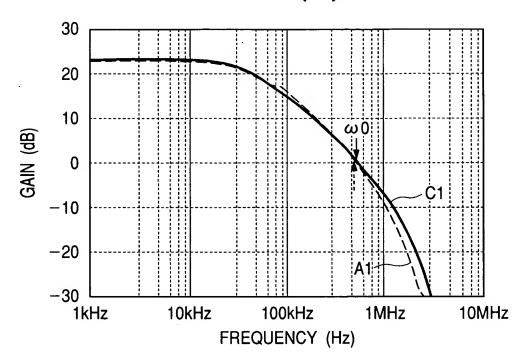
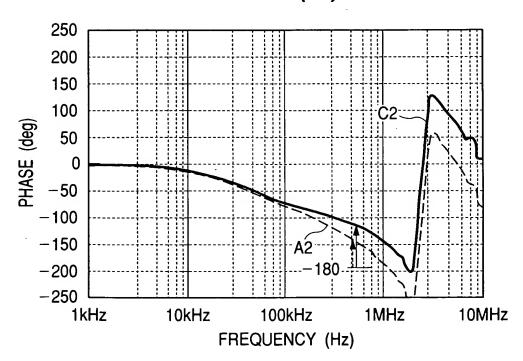
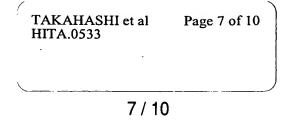
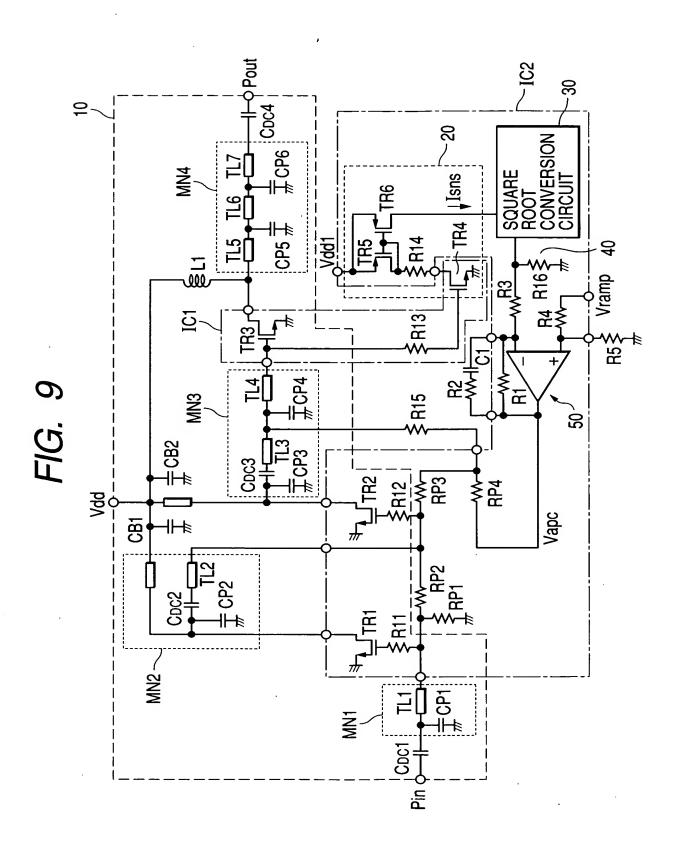
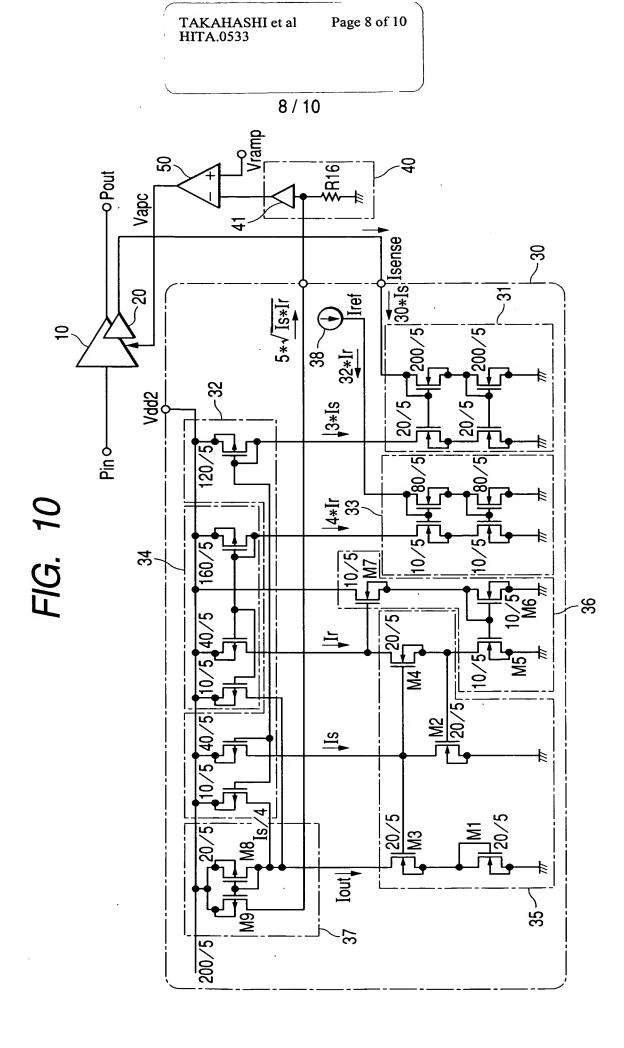


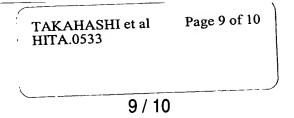
FIG. 8(B)











-ANT 198 -200 120b 410b 120a FF. LPF SAW SAW FIG. 11 Vramp, Mode 200 Pout GSM DCS CPU GSM GSM PA 210a DAC RF IC 300 BASEBAND IC O

TAKAHASHI et al Page 10 of 10 HITA.0533

FIG. 12

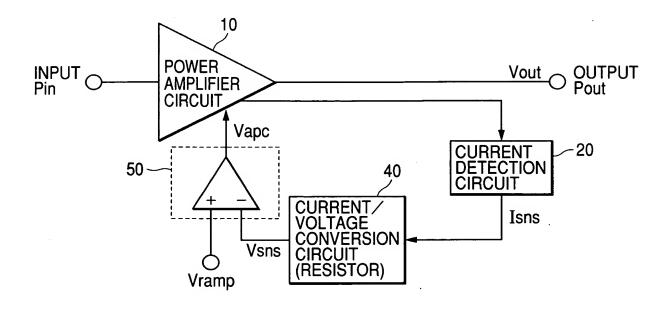


FIG. 13

